L Number	Hits	Search Text	DB	Time stamp
1	4	((reinforce or reinforcing) adj pad) and (chip or die) and (substrate or pcb or pwb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 15:54
2	5	"288978"	JPO; DERWENT	2002/08/07 15:35
3	0	"110288978"	JPO; DERWENT	2002/08/07 15:36
4	2	"11288978"	JPO; DERWENT	2002/08/07 15:53
5	0	6316735.URPN.	USPAT	2002/08/07 15:52
6	0	6316735.URPN.	USPAT	2002/08/07 15:53
7	5355	(chip or die) and (substrate or pcb or pwb) and (pad same (ball or bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 17:13
8	1018	((chip or die) and (substrate or pcb or pwb) and (pad same (ball or bump))) and ((shape or rounded or round or cross or v) with pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 16:30
9	882	(((chip or die) and (substrate or pcb or pwb) and (pad same (ball or bump))) and ((shape or rounded or round or cross or v) with pad)) and (@ad<20010213)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 16:32
10	0	20020089057.URPN.	USPAT	2002/08/07 16:06
11	119	((chip or die) and (substrate or pcb or pwb) and (pad same (ball or bump))) and (recess with pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 16:08
12	3460	(chip or die) and (substrate or pcb or pwb) and (pad same (balls or bumps))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 16:30
13	693	((chip or die) and (substrate or pcb or pwb) and (pad same (balls or bumps))) and ((shape or rounded or round or cross or v) with pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 16:30
14	610	(((chip or die) and (substrate or pcb or pwb) and (pad same (balls or bumps))) and ((shape or rounded or round or cross or v) with pad)) and (@ad<20010213)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 17:11
15	0	6177636.URPN.	USPAT	2002/08/07 16:53
16	17	("3465435" | "4067104" | "4466184" | "4642889" | "4818728" | "4825539" | "4955523" | "4961259" | "5067007" | "5133495" | "5148265" | "5148266" | "5203075" | "5213676" | "5316788" | "5354205" | "5455390").PN.	USPAT	2002/08/07 16:53
19	1	5844314.URPN.	USPAT	2002/08/07 17:05
20	2	("5042919" | "5084961").PN.	USPAT	2002/08/07 17:05
21	243	((plurality near (balls or ball or bump or bumps)) same pad) and (@ad<20010213)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 17:13
22	119	(((plurality near (balls or ball or bump or bumps)) same pad) and (@ad<20010213)) and ((chip or die) and (substrate or pcb or pwb))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 17:15
23	1	5849132.URPN.	USPAT	2002/08/07 17:22

L Number	Hits	Search Text	DB	Time stamp
1	77	((x or cross) and 1 and v) with pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 19:43
2	37	(((x or cross) and 1 and v) with pad) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 19:42
3	1022	(shape with pad) and (ball or bump) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 19:48
4	880	((shape with pad) and (ball or bump) and (chip or die)) and (@ad<20010213)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 20:18
5	0	6313541.URPN.	USPAT	2002/08/07 19:54
6	6	("5844317" | "5891745" | "5962919" | "5981302" | "6130459" | "6181016").PN.	USPAT	2002/08/07 19:54
7	11	5929521.URPN.	USPAT	2002/08/07 19:59
8	1061	257/737.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 20:13
9	828	257/738.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 20:14
10	567	438/613.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 20:14
11	1723	438/614.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 20:14
12	151	438/615.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 20:14
14	171	438/617.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 20:14
13	77	438/616.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 20:17
15	0	228/108.22.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 20:17

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16	0	228/108.21.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 20:18
17	35312	228/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 20:18
18	2735	228/$.ccls. and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 20:18
19	1289	(228/$.ccls. and pad) and (ball or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 20:19
20	1056	((228/$.ccls. and pad) and (ball or bump)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 20:18
21	1000	(((228/$.ccls. and pad) and (ball or bump)) and (chip or die)) and (@ad<20010213)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 20:18
22	610	((((228/$.ccls. and pad) and (ball or bump)) and (chip or die)) and (@ad<20010213)) and (pad with (ball or bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 20:19